

Power Inductor



BQJM Series



Overview

Closed Magnetic Circuit Type Thin-film Molding Process for Power Inductor.

Smaller size and low profile, providing high saturation current

Bottom termination, good welding reliability, Low DC Resistance & Higher Saturation Current

Benefits

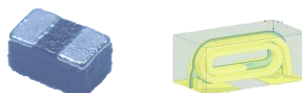
1. Thin-film Molding Process for Power Inductor
2. Smaller size and low profile, providing high saturation current
3. Low DC Resistance & Higher Saturation Current

Applications

1. Consumer Electronics
2. Communications

Product Information

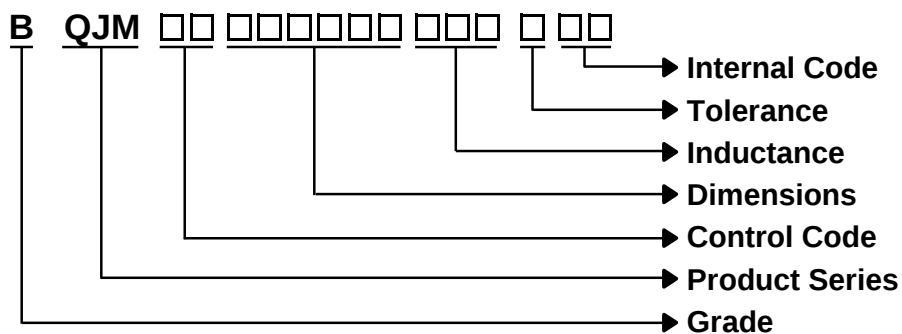
Series	L (mm)	W(mm)	T (mm)	Inductance (μH)
BQJM	1.0	0.5	0.65	0.47, 1.0
	1.0	0.5	0.8	



BQJM00100508 Series Specification

1 Scope: This specification applies to Molding power inductors.

2 Part numbering



3 Temperature rating

Operating Temperature: - 55°C~125°C

Storage Temperature: (on tape & reel): -20°C to +40°C; 75% RH max.

4 Marking

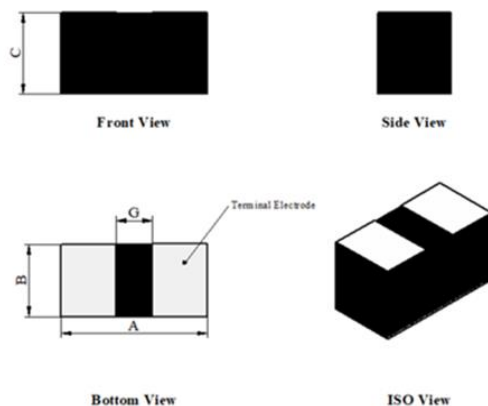
No Marking

5 Standard testing condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

BQJM00100508 Series Specification

6 Configuration and dimensions



Dimensions in mm

Type	100508
A	1.0 ± 0.2
B	0.5 ± 0.2
C	0.80 Max.
G	0.25Typ.

Size Code	Net weight(grms)
100508	0.0026g(typ.)

7 Electrical characteristics

Part number	Inductance (uH)	Tolerance (±%)	Test Freq.	I _{rms} (A) Max.(Typ.)	I _{sat} (A) Max.(Typ.)	RDC(mΩ) Max.(Typ.)
BQJM001005081R0MP0	1.00	20	1MHz,0.2V	0.8(1.0)	0.6(0.8)	280(250)

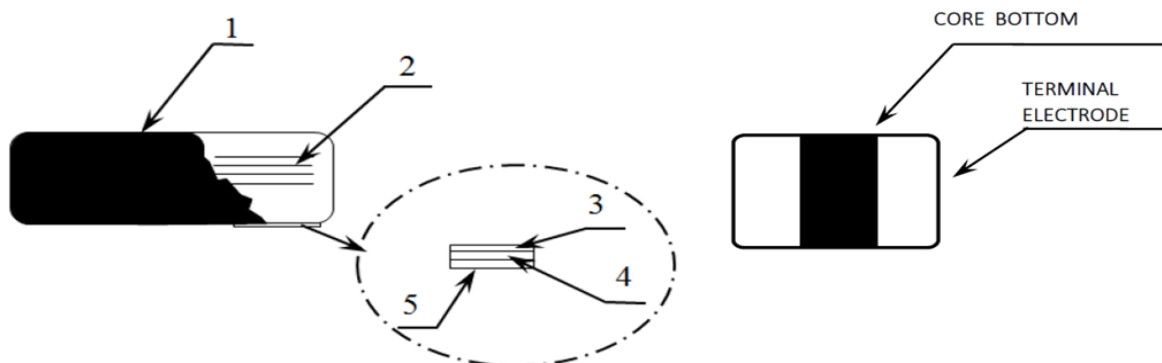
Note:

1. Operating temperature range -55°C to 125°C.
2. I_{sat} for Inductance drop 30% from its value without current.
3. I_{rms} for a 40°C temperature rise from 25°C ambient.
4. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.
Circuit design 125°C under worst case operating conditions. Component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

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8.1 Construction



8.2 Material list

No	Part	Maerial
1	Core	Metal
2	Wire	Copper Wire
3	Plating	Cu
4	Plating	Ni
5	Plating	Sn

BQJM00100508 Series Specification

9 Reliability test items

1-1.Mechanical performance

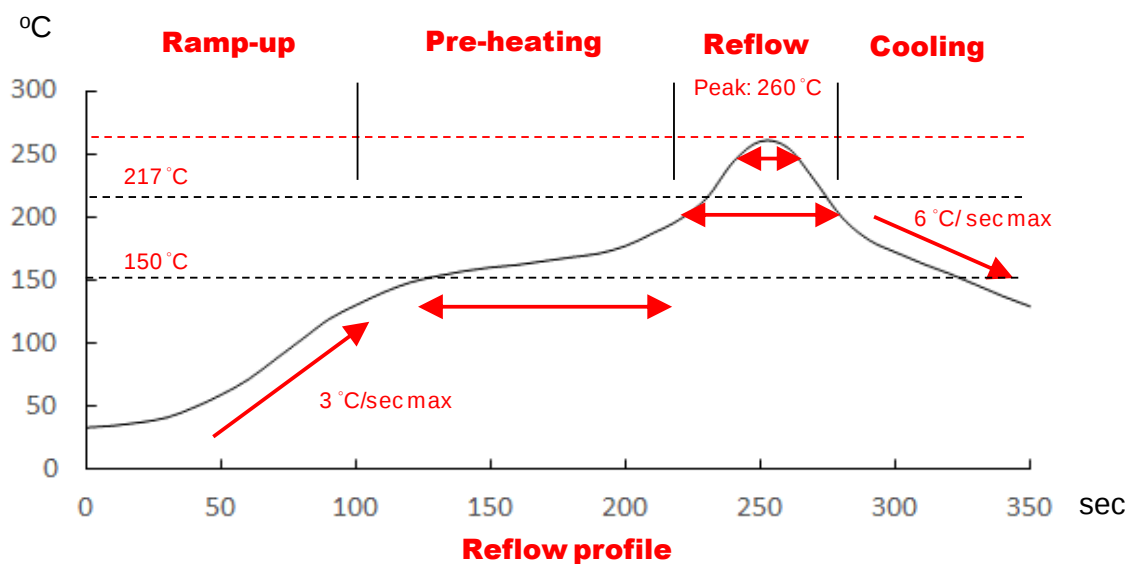
No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the metal body	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec
1-1-2	Vibration	Appearance:No damage (for microscope of CASTOR MZ-45 20X) Inductance change shall be within $\pm 20\%$	Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Inductance: within $\pm 20\%$ of initial value	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260 $\pm 5^\circ\text{C}$ Immersion Time: 10 ± 1 sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245 $\pm 5^\circ\text{C}$ Immersion Time: 4 ± 1 sec
1-1-5	Terminal Strength Test	No split termination	Test device shall be soldered on the substrate, then apply a force in the direction of the arrow. Force : 5N Keeping Time: 10 ± 1 sec

1-2.Environmental performance

No	Item	Specification	Test Method		
1-2-1	Temperature Cycle	Appearance: No damage Inductance:within±20% of initial value	One cycle:		
			Step	Temperature (℃)	Time (min)
			1	-40±3	30
			2	25±2	3
			3	125±3	30
			4	25±2	3
			Total: 100cycles Measured after exposure in the room condition for 24hrs		
1-2-2	Humidity Resistance		Temperature: 60±2℃ Relative Humidity: 90 ~ 95% / Time: 500hrs Measured after exposure in the room condition for 24hrs		
1-2-3	High Temperature Resistance		Temperature: 85±3℃ Relative Humidity: 0% / Time: 500hrs Measured after exposure in the room condition for 24hrs		
1-2-4	Low Temperature Resistance		Temperature: -40±3℃ Relative Humidity: 0% / Time: 500hrs Measured after exposure in the room condition for 24hrs		

BQJM00100508 Series Specification

10 Recommended IR reflow profile



Lead-Free(LF)

Refer to J-STD-020C

Item	Ramp-up	Pre-heating	Reflow	Peak Temp.	Cooling
Temp. scope	R.T. ~150 °C	150 °C~200 °C	217 °C	260±5 °C	Peak Temp. 150 °C
Time spec	-	60~180 sec	60~150 sec	20~40 sec	-
Time result	-	75~100 sec	90~120 sec	20~35 sec	-

Note:

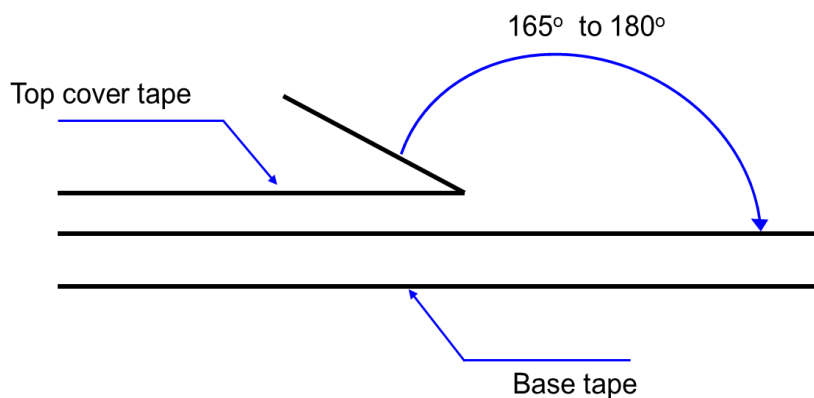
1. IR reflow times: within 3 times.
2. Nitrogen adopted is recommended while in IR reflow.

BQJM00100508 Series Specification

11 Packaging

11.1 Packaging- cover tape

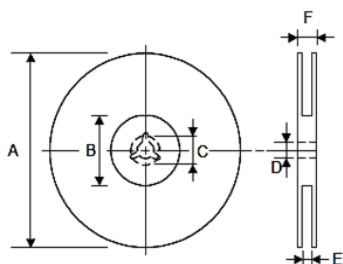
The force for tearing off cover tape is 10 to 130 grams.



11.2 Packaging quantity

Type	Pcs/Reel
100508	3000

11.3 Reel dimensions



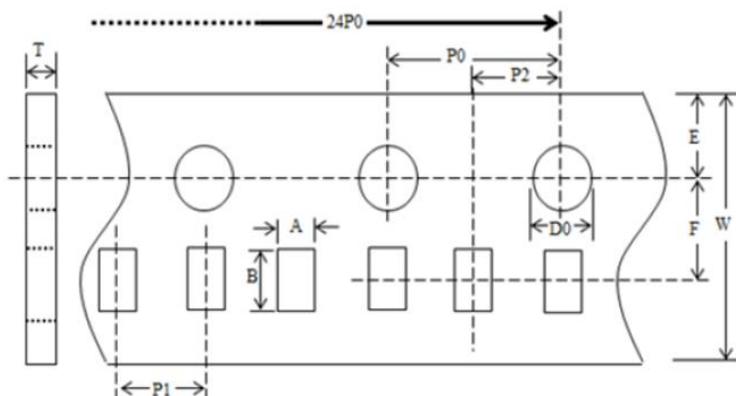
Dimensions in mm

Type	A	B	C	D	E	F
100508	178	60	12	1.5	8.4	13.4

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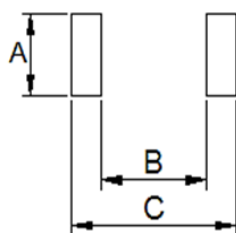
11 Packaging

11.4 Tape dimensions in mm



TYPE	A	B	W	P1	K
100508	0.75±0.05	1.34±0.05	8±0.1	2.0±0.1	-
	P0	P2	D0	E	T
	4.0±0.1	2.0±0.05	1.55±0.05	1.75±0.05	0.85±0.03

12 Recommended pattern



Dimensions in mm

Type	A	B	C
100508	0.7	0.5	1.3

13 Note

1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
2. Don't design/mount any components in contact with this product
3. The moisture sensitivity level (MSL) of products is classified as level 1.
4. Shelf life: 1years from the date of shipment.

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14 Graph

